Product Change Notification - GBNG-03JJNM850

Date:

05 Mar 2020

Product Category:

Car Access

Affected CPNs:

Notification subject:

CCB 3944 Initial Notice: Qualification of MMT as an additional assembly site for selected Atmel ATA5702xx and ATA5700xx device families available in 38L VQFN (5x7x1mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Notification text:

PCN Status:

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected Atmel ATA5702xx and ATA5700xx device families available in 38L VQFN (5x7x1mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ASCL assembly site using AuPd1 bond wire and EN-4900 die attach material.

Post Change:

Assembled at ASCL assembly site using AuPd1 bond wire and EN-4900 die attach material or assembled at MMT assembly site using palladium coated copper with gold flash (CuPdAu) bond wire and 3280 die attach material.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)	Microchip Technology Thailand (Branch) / MMT
Wire material	AuPd1	AuPd1	CuPdAu
Die attach material	EN-4900	EN-4900	3280
Molding compound material	G700	G700	G700
Lead frame material	C194	C194	C194

Impacts to Data Sheet:

Yes. POD (package outline drawing) update.

All units in millimeter (mm)		ASE Group Chung-Li (ASCL)			Microchip Technology Thailand (Branch) / MMT		
Dimension	Symbol	Min	Nom	Max	Min	Nom	Max
Overall height	A	0.80	0.85	0.90	0.80	0.90	1.00
Wettable flank step length	D3	-	-	0.40	-	-	0.085

Wettable flank step height	A4	0.10	-	0.15	0.10	-	0.19

Change Impact:
None
Reason for Change:
To improve on-time delivery and performance by qualifying MMT as an additional assembly site.
Change Implementation Status:
In Progress
Estimated Qualification Completion Date:
July 2020

Time Table Summary:

	March 2020					-->	July 2020					
Workweek	10	11	12	13	14		27	28	29	30	31	
Initial PCN Issue Date	X											
Qual Report Availability											X	
Final PCN Issue Date											X	

Method to Identify Change:
Traceability code
Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.
Revision History:
March 05, 2020: Issued initial notification.
The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.
Attachment(s):
PCN_GBNG-03JJNM850_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATA5702F1000M-WDQW

ATA5700F1000M-WDQW

ATA5702F1000M-WDQW-VAO

ATA5700F1000M-WDQW-VAO